SUBSTRATE TRANSPORT METHOD AND SUBSTRATE TRANSPORT APPARATUS

ABSTRACT OF THE DISCLOSURE

A wafer is formed by molding two or more chips arranged planarly with a resin. The wafer is joined to a support plate via a double-faced adhesive tape having an adhesive layer on one side with a heating separation property, whereby a workpiece is formed. The workpiece is subjected to a given process, and then is heated on a first table for removing the support plate with a support-plate removing device. The wafer removed from the double-faced adhesive tape includes the resin in a softened state. The wafer is then transported while outer periphery on a surface of the wafer on a resin side is suction-held with a suction plate. During transporting the wafer, pressure within the suction head is adjusted in accordance with displacement in level of the wafer.

Figure 18